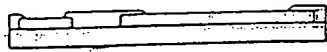


Fig. 1A

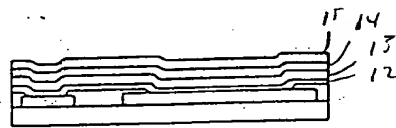


11

Non-Passivated Die

Fig. 1B

11



Sputter Ti/Cu/Ti/Cu

Fig. 1C

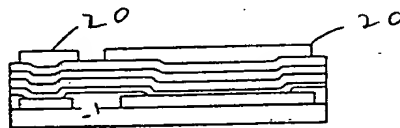
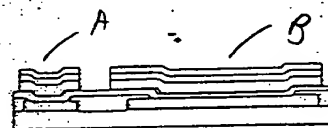


Photo Process, Isolation

Fig. 1D



Isolation Etch, Cu/Ti/Cu

Fig. 1E

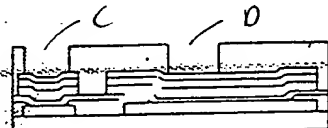
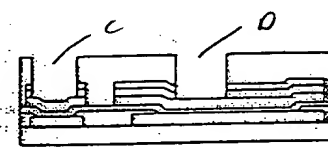


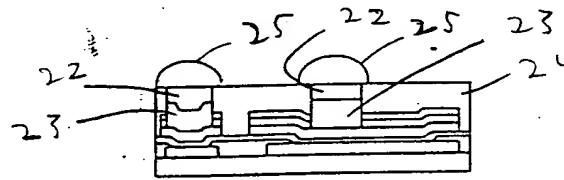
Photo Process, UBM of Bump

Fig. 1F



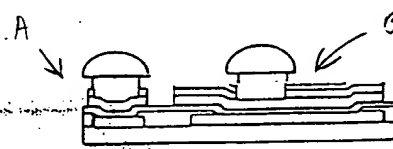
Cu/Ti Etching

Fig. 1G



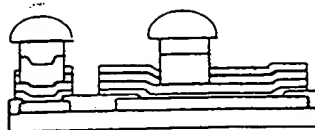
Plating, Cu, Solder

Fig. 1H



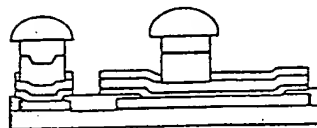
PR Stripping

Fig. 1I



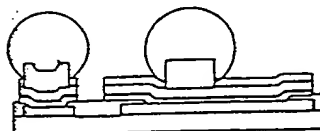
Ti Etching at isolation

Fig. 1J



Cu Etching

Fig. 1K



Solder Reflow

Downloaded from ascelibrary.org by Seattle University on 06/11/15. Copyright ASCE, For All Rights Reserved, No part of this document may be reproduced without written permission from ASCE.